

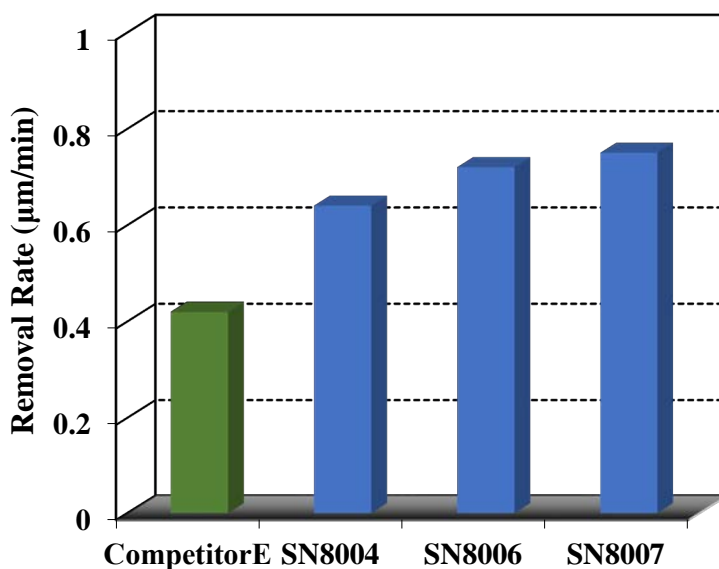
Reclaim wafer CMP SN8004

Physical Properties for SN8004-series Slurries

Item	Competitor E	SN8004	SN8006	SN8007
pH	9.86	11.02	10.80	10.86
Solid Content (%)	43.08	40.16	40.35	40.26
Mean Particle Size (nm)	52.6	80.1	84.4	89.5
Removal Rate ($\mu\text{m}/\text{min}$)	0.42	0.65	0.7	0.75
Over-Etching on Surface	No	No	No	No

Note ①: with 1:2 dilute for polishing reclaim wafers (32" Speedfam tool) with 2.0 kgf/cm² down force and 40 rpm/min rotation speed

Removal Rates for SN8004-series Slurries



Reclaim CMP slurries provide higher removal rates by 30-50% enhancement and better polishing performance than the competitor E.

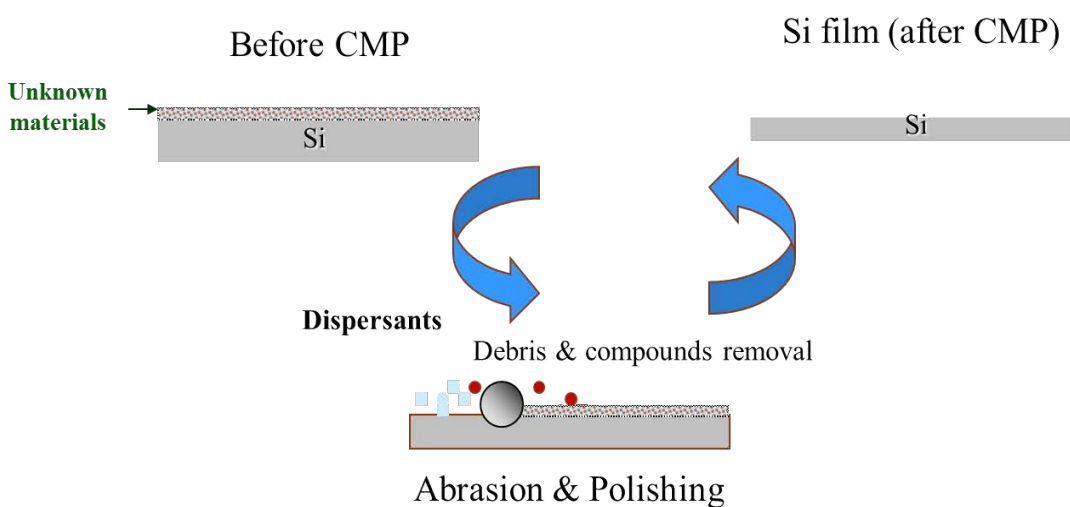
Reclaim Wafer Slurry SN8005

Benefits of SN8005

SN8005 products meet the following critical performance criteria:

- **Alumina-based alkaline slurry**
- **Better polishing capability for complex hard films**
- **High removal rates (RRs)**
- **High throughput**
- **Low defectivity**
- **Good surface roughness**
- **Excellent slurry stability and shelf-life**

Reaction Mechanism for SN8005 Slurries



CMP: Chemical Forces + Mechanical Forces, Mechanical dominate!

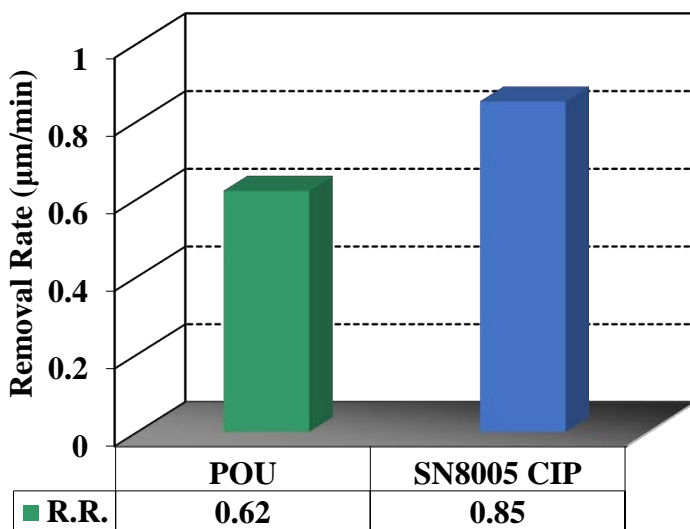
Reclaim Wafer CMP SN8005

Physical Properties for SN8005 Slurries

Item	POU	SN8005-CIP
pH	10.92	10.5
Solid Content (%)	11.02	10.58
Mean Particle Size (nm)	600 ~ 800	300 ~ 500
Removal Rate ($\mu\text{m}/\text{min}$) ①	0.62	0.85
Dispersing ability	Poor	Best

Note ①: with 1:2 dilute for polishing reclaim wafers (32" Speedfam tool) with 2.0 kgf/cm² down force and 40 rpm/min rotation speed

Removal Rates of SN8005-series



The new slurry product of SN8005 CIP is enhanced by the removal rate for 30-40%.